

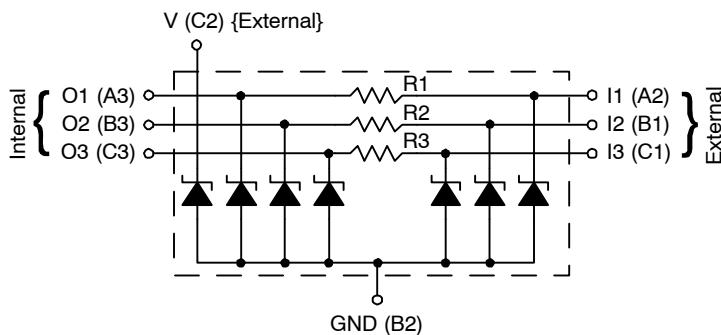
CM6305

EMI Filter with ESD Protection for SIM Card Applications

Product Description

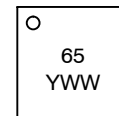
The CM6305 is a 3 x 3, 8-bump EMI filter with ESD protection device for SIM card applications in a 0.4 mm pitch CSP form factor. It is fully compliant with IEC 61000-4-2. The CM6305 is also RoHS II compliant.

ELECTRICAL SCHEMATIC



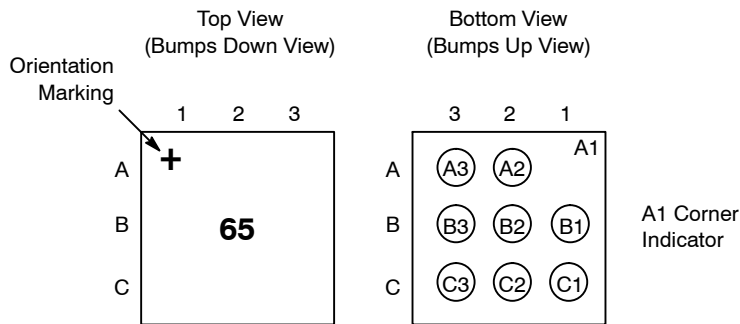
WLCSP8
CASE 567CE

MARKING DIAGRAM



65 = CM6305
YWW = Date Code

PACKAGE / PINOUT DIAGRAMS



ORDERING INFORMATION

Device	Package	Shipping†
CM6305	WLCSP-8 (Pb-Free)	5000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Table 1. PIN DESCRIPTIONS

Pin	Description	Pin	Description
A2	Channel 1 External	A3	Channel 1 Internal
B1	Channel 2 External	B3	Channel 2 Internal
C1	Channel 3 External	C3	Channel 3 Internal
B2	GND	C2	V External

CM6305

ELECTRICAL SPECIFICATIONS AND CONDITIONS

Table 2. PARAMETERS AND OPERATING CONDITIONS

Parameter	Rating	Units
Storage Temperature Range	-55 to +150	°C
Operating Temperature Range	-40 to +85	°C
Power Dissipation at 70°C per Channel	60	mW

Table 3. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
R ₁	Resistance		80	100	120	Ω
R ₂	Resistance		37.6	47	56.4	Ω
R ₃	Resistance		80	100	120	Ω
I _{LEAK}	Leakage Current per Channel	V _{IN} = 3.0 V		10	100	nA
C	Capacitance on Filter Channels 1, 2 and 3	At 1 MHz, V _{IN} = 0 V	8	10	12	pF
	Capacitance on Clamp Channel (pin C2)	At 1 MHz, V _{IN} = 0 V	8	10	12	pF
V _B	Breakdown Voltage (Positive)	I _R = 1 mA	6	7	9	V
V _{ESD}	ESD Protection Peak Discharge Voltage at A2, B1 and C1 pins a) Contact Discharge per IEC 61000-4-2 standard b) Air Discharge per IEC 61000-4-2 standard	(Note 2)	±8 ±15			kV
	ESD Protection Peak Discharge Voltage at C2 pin a) Contact Discharge per IEC 61000-4-2 standard b) Air Discharge per IEC 61000-4-2 standard	(Note 2)	±15 ±15			kV
	ESD Protection Peak Discharge Voltage at A3, B3 and C3 pins a) Contact Discharge per IEC 61000-4-2 standard b) Air Discharge per IEC 61000-4-2 standard	(Note 2)	±2 ±2			kV

- All parameters specified at T_A = 25°C unless otherwise noted.
- Standard IEC 61000-4-2 with C_{Discharge} = 150 pF, R_{Discharge} = 330 Ω.

Table 4. CSP TAPE AND REEL SPECIFICATIONS †

Part Number	Chip Size (mm)	Pocket Size (mm) B ₀ X A ₀ X K ₀	Tape Width W	Reel Dia.	Qty Per Reel	P ₀	P ₁
CM6305	1.16 X 1.16 X 0.60	1.27 X 1.27 X 0.69	8 mm	178 mm (7")	5000	4 mm	4 mm

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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RF CHARACTERISTICS

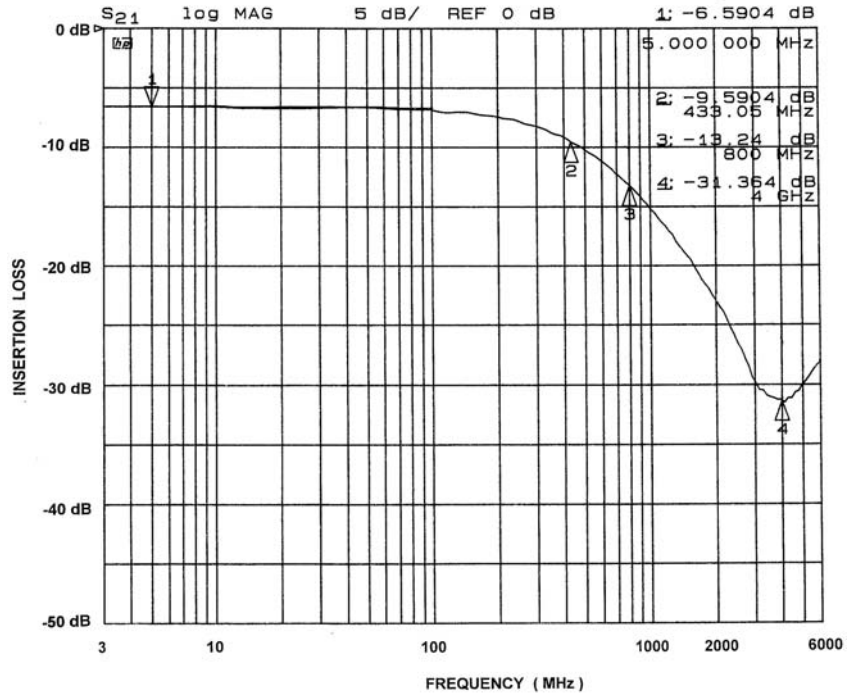


Figure 1. Insertion Loss, Filter 1 (pins A2, A3) and Filter 3 (pins C1, C3) (Bias = 0 V, $T_A = 25^\circ\text{C}$)

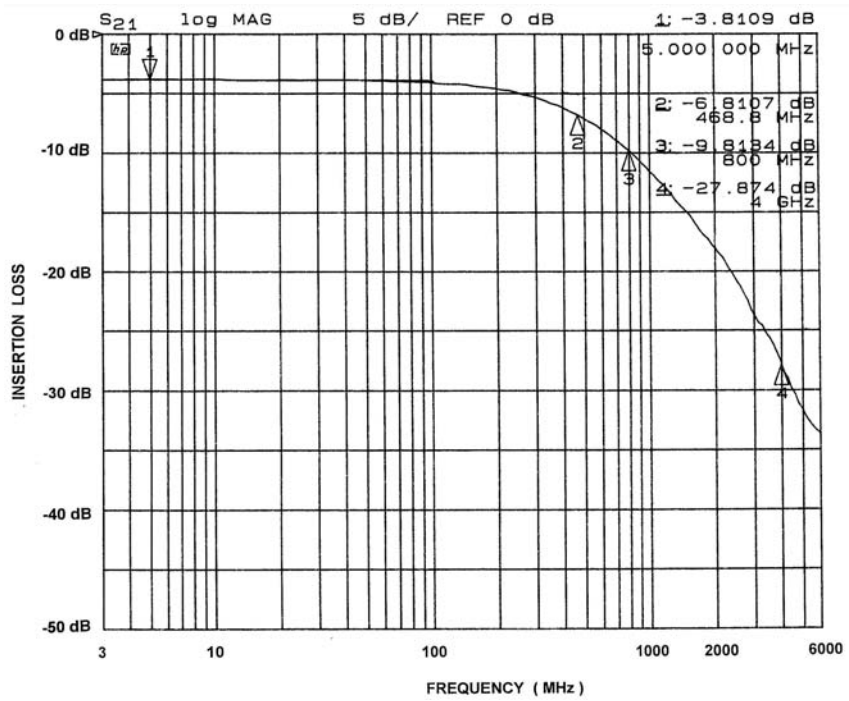
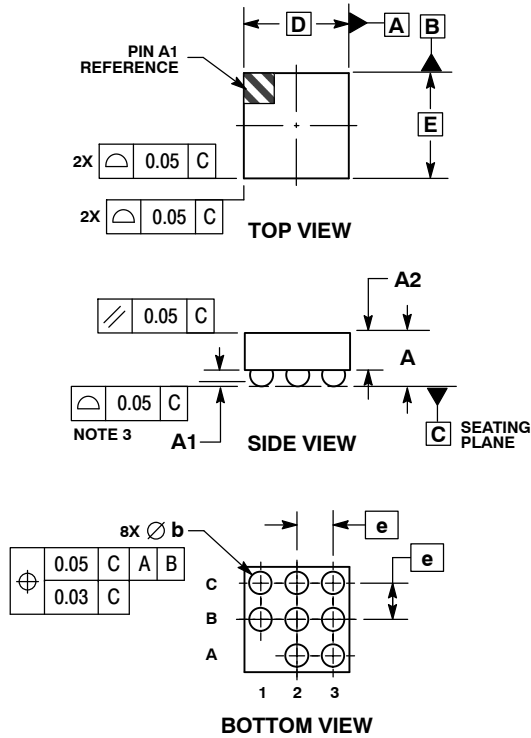


Figure 2. Insertion Loss, Filter 2 (pins B1, B3) (Bias = 0 V, $T_A = 25^\circ\text{C}$)

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PACKAGE DIMENSIONS

WLCSP8, 1.16x1.16
CASE 567CE
ISSUE O

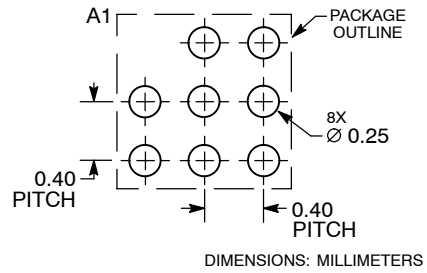


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.57	0.63
A1	0.17	0.24
A2	0.41 REF	
b	0.24	0.29
D	1.16 BSC	
E	1.16 BSC	
e	0.40 BSC	

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.